

**IGBT** 

# SGW5N60RUFD

## **Short Circuit Rated IGBT**

## **General Description**

Fairchild's RUFD series of Insulated Gate Bipolar Transistors (IGBTs) provide low conduction and switching losses as well as short circuit ruggedness. The RUFD series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

### **Features**

- Short circuit rated 10us @  $T_C = 100$ °C,  $V_{GE} = 15$ V
- · High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.2 \text{ V} @ I_C = 5A$
- · High input impedance
- CO-PAK, IGBT with FRD : t<sub>rr</sub> = 37ns (typ.)

## **Applications**

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		SGW5N60RUFD	Units	
V <sub>CES</sub>	Collector-Emitter Voltage		600	V	
$V_{GES}$	Gate-Emitter Voltage		± 20	V	
_	Collector Current	@ T <sub>C</sub> = 25°C	8	Α	
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	5	Α	
I <sub>CM (1)</sub>	Pulsed Collector Current		15	Α	
I <sub>F</sub>	Diode Continuous Forward Current	@ T <sub>C</sub> = 100°C	8	Α	
I <sub>FM</sub>	Diode Maximum Forward Current		56	Α	
T <sub>SC</sub>	Short Circuit Withstand Time	@ T <sub>C</sub> = 100°C	10	us	
$P_{D}$	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	60	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	25	W	
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C	

### Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

## **Thermal Characteristics**

Symbol	Parameter		Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		2.0	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		3.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)		40	°C/W

### Notes :

(2) Mounted on 1" squre PCB (FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
$\Delta B_{VCES}/$ $\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$		0.6		V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Chai	racteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 5mA$ , $V_{CE} = V_{GE}$	5.0	6.0	8.5	V
	Collector to Emitter	$I_{C} = 5A, V_{GE} = 15V$		2.2	2.8	V
V <sub>CE(sat)</sub>	Saturation Voltage	I <sub>C</sub> = 8A, V <sub>GE</sub> = 15V		2.5		V
Dynami	c Characteristics					
C <sub>ies</sub>	Input Capacitance	V 20V V 0V		354		рF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$ f = 1MHz		67		pF
C <sub>res</sub>	Reverse Transfer Capacitance	- 1 = 11VII 12		14		pF
t <sub>d(on)</sub>	Turn-On Delay Time			13		ns
t <sub>r</sub>	Rise Time	-		24		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 5\text{A},$		34	50	ns
t <sub>f</sub>	Fall Time	$R_G = 40\Omega$ , $V_{GE} = 15V$ ,		136	200	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C		88		uJ
E <sub>off</sub>	Turn-Off Switching Loss			107		uJ
E <sub>ts</sub>	Total Switching Loss	1		195	280	uJ
t <sub>d(on)</sub>	Turn-On Delay Time			13		ns
t <sub>r</sub>	Rise Time	1		26		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 5\text{A},$		40	60	ns
t <sub>f</sub>	Fall Time	$R_G = 40\Omega, V_{GE} = 15V,$		250	350	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C		103		uJ
E <sub>off</sub>	Turn-Off Switching Loss			220		uJ
E <sub>ts</sub>	Total Switching Loss			323		uJ
T <sub>sc</sub>	Short Circuit Withstand Time	V <sub>CC</sub> = 300 V, V <sub>GE</sub> = 15V @ T <sub>C</sub> = 100°C	10			us
$Q_g$	Total Gate Charge	V <sub>CE</sub> = 300 V, I <sub>C</sub> = 5A,		16	24	nC
$Q_{ge}$	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 3A,$ - $V_{GF} = 15V$		3	6	nC
$Q_{gc}$	Gate-Collector Charge	GE - 100		7	14	nC
9 -				7.5		

# Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V	Diode Forward Voltage	I QA	$T_C = 25^{\circ}C$		1.4	1.7	V
$V_{FM}$	Didde Forward Voltage	I <sub>F</sub> = 8A	T <sub>C</sub> = 100°C		1.3		V
	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		37	55	ns
t <sub>rr</sub>			T <sub>C</sub> = 100°C		55		
	Diode Peak Reverse Recovery	I <sub>F</sub> = 8A,	$T_C = 25^{\circ}C$		3.5	5.0	۸
<sup>I</sup> rr	Current	di/dt = 200 A/us	T <sub>C</sub> = 100°C		4.5		Α
Q <sub>rr</sub>	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		65	138	nC
			T <sub>C</sub> = 100°C		124		1110

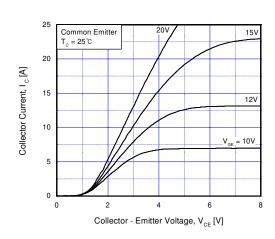
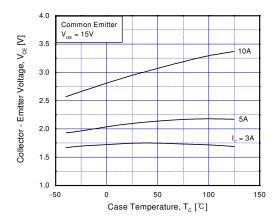


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



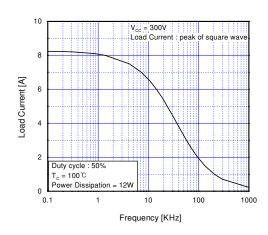
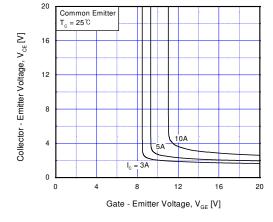


Fig 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



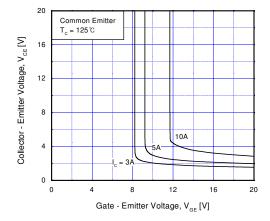


Fig 5. Saturation Voltage vs.  $V_{\text{GE}}$ 

Fig 6. Saturation Voltage vs.  $V_{\text{GE}}$ 

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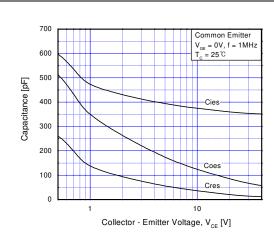
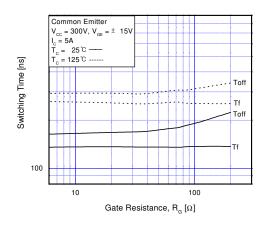


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



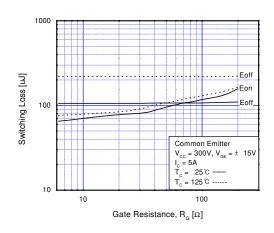
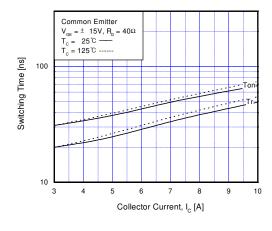


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



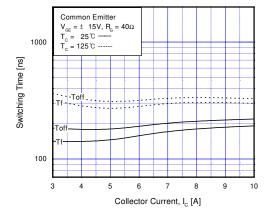
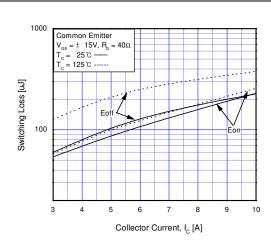


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



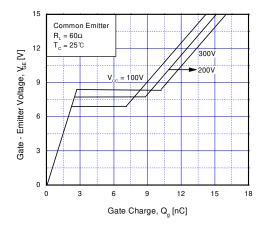
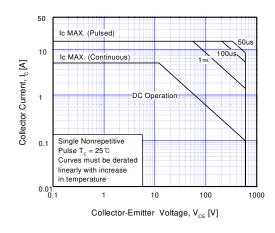


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



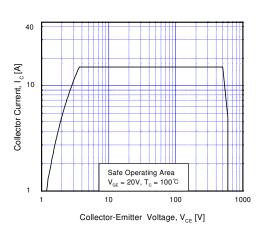


Fig 15. SOA Characteristic

Fig 16. Turn-Off SOA Characteristics

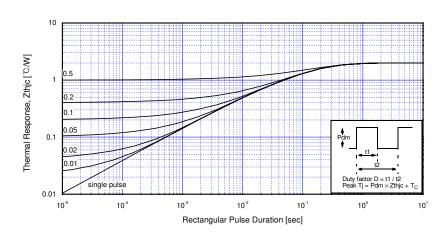
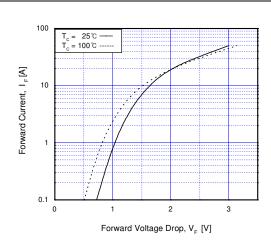


Fig 17. Transient Thermal Impedance of IGBT

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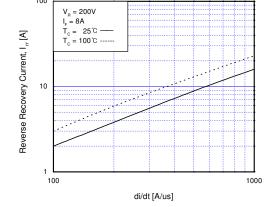
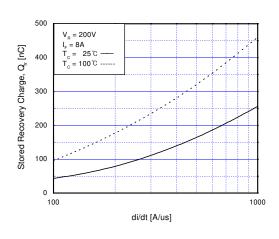


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



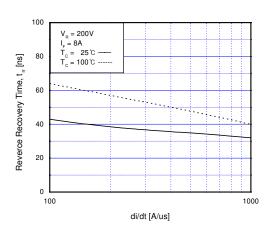
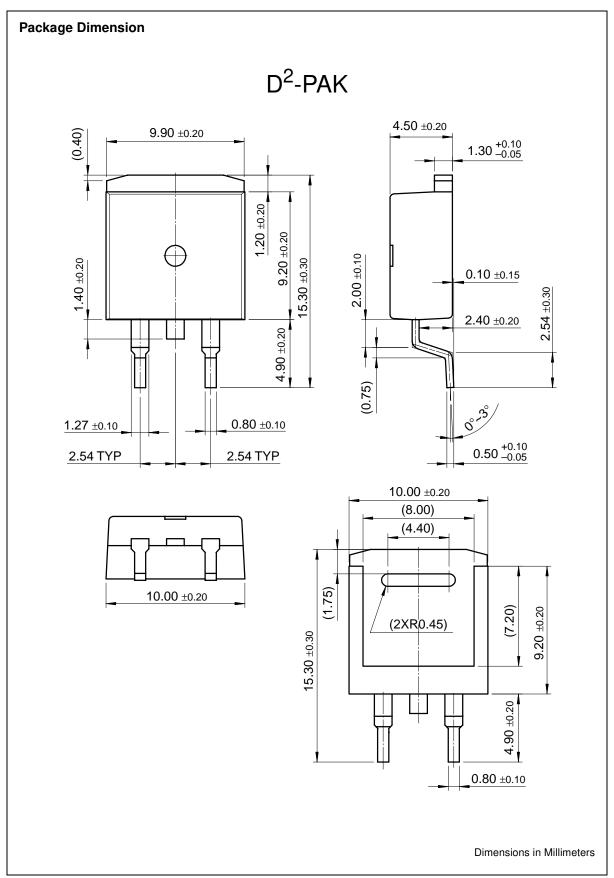


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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Product	<b>Product status</b>	Pricing*	Package type	Leads	Packing method
SGW5N60RUFDTM	Full Production	\$1.45	TO-263(D2PAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

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